

3. (original) The electrode according to claim 2, wherein at least one portion of the electrically conductive support substrate is bonded to the diamond-coated silicon.

4. (original) The electrode according to claim 2, wherein at least one surface of the electrically conductive support substrate is bonded to the diamond-coated silicon.

5. (currently amended) The electrode according to claim 3 or 4, wherein the electrically conductive support substrate is bonded to the diamond-coated silicon with an electrically conductive bonding material.

6. (currently amended) The electrode according to ~~any one of claims 3 to 5~~ claim 3, wherein the bonding is performed by welding or adhesion.

7. (new) The electrode according to claim 4, wherein the electrically conductive support substrate is bonded to the diamond-coated silicon with an electrically conductive bonding material.

8. (new) The electrode according to claim 4, wherein the bonding is performed by welding or adhesion.

9. (new) The electrode according to claim 5, wherein the bonding is performed by welding or adhesion.